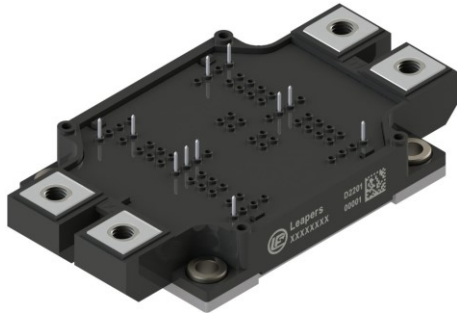


Description

The DFS300HF12I3C2 is a Half Bridge SiC MOSFET Power Module. It integrates high performance SiC MOSFET chips designed for the applications such as Motor drives and Renewable energy.



Features

- 1200V/7.2mΩ
- Low thermal resistance with Si₃N₄ AMB
- 175°C maximum junction temperature
- Low inductive design
- Thermistor inside
- Pressfit terminal
- Copper base size: 79mm*62mm

Applications

- xEV Applications
- Motor Drive
- Vehicle Fast Chargers
- Renewable energy

Circuit diagram

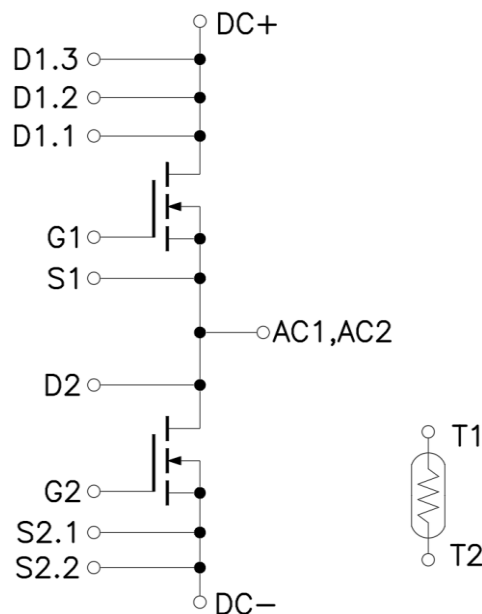


Figure 1. Out drawing & circuit diagram for DFS300HF12I3C2

Pin Configuration and Marking Information

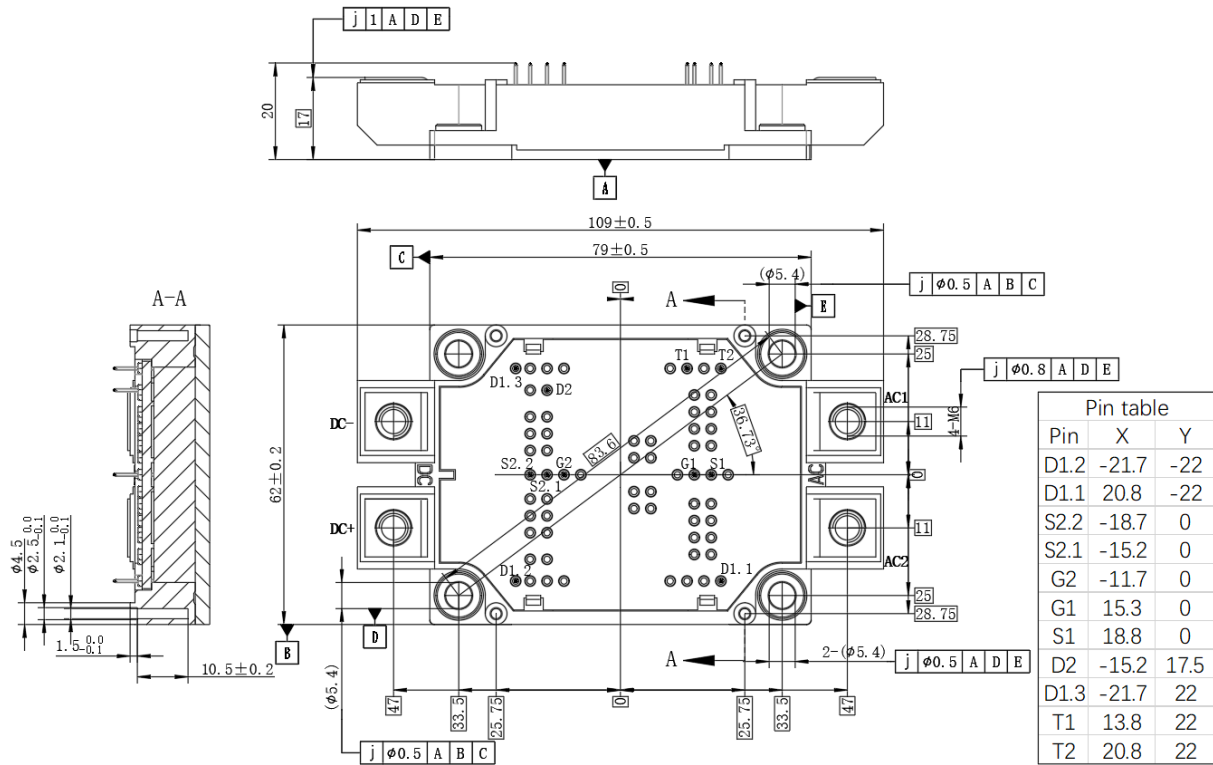


Figure 2. Pin configuration

Module

Parameter	Conditions	Value	Unit
Isolation Voltage	RMS, f =50Hz, t =1min	3.4	KV
Material of module baseplate	-	Cu	-
Creepage distance	terminal to heatsink terminal to terminal	14.5 10	mm
Clearance	terminal to heatsink terminal to terminal	12.5 10	mm
CTI	-	>400	-
Module lead resistance, terminals – chip	T _C =25°C	0.3	mΩ
Mounting torque for module mounting	M5, M6	3 to 6	Nm
Weight	-	250	g

Maximum Ratings ($T_j = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Unit
V_{DS}	Drain-Source Voltage	G-S Short	1200	V
V_{GS}	Gate-Source Voltage	D-S Short, AC frequency $\geq 1\text{Hz}$, Note1	-10 to 20	V
I_{DS}	DC Continuous Drain Current	$T_f = 25^\circ\text{C}$, $V_{GS} = +15\text{V}$	320	A
I_{DS}	DC Continuous Drain Current	$T_f = 65^\circ\text{C}$, $V_{GS} = +15\text{V}$	280	A
I_{SD}	Source (Body diode) Current	$T_f = 25^\circ\text{C}$, with ON signal	320	A
I_{SD}	Source (Body diode) Current	$T_f = 65^\circ\text{C}$, with ON signal	280	A
I_{DSM}	Pulse Drain Current	$T_c = 65^\circ\text{C}$, Pulse width = 1ms, $V_{GS} = +15\text{V}$, Note2	600	A
P_{tot}	Total Power Dissipation	$T_c = 25^\circ\text{C}$	1300	W
T_{jmax}	Max Junction Temperature	-	175	$^\circ\text{C}$
T_{stg}	Storage Temperature	-	-40 to 125	$^\circ\text{C}$

Note1: Recommended Operating Value, +15V/-5V, +15V/-4V

Note2: Pulse width limited by maximum junction temperature

NTC characteristics

Symbol	Parameter	Condition	Value			Unit
			Min.	Typ.	Max.	
R_{25}	Resistance	$T_c = 25^\circ\text{C}$	-	5	-	$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_c = 100^\circ\text{C}$, $R_{100} = 493\Omega$	5	-	5	%
P_{25}	Power dissipation	$T_c = 25^\circ\text{C}$	-	-	20	mW
$B_{25/50}$	B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3375	-	K
$B_{25/80}$	B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3411	-	K
$B_{25/100}$	B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	-	3433	-	K

MOSFET Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =300uA		1200	-	-	V
I _{DSS}	Zero gate voltage drain Current	V _{DS} =1200V, V _{GS} =0V		-	3	-	μA
V _{GS(th)}	Gate-source threshold Voltage	I _D =105mA, V _{DS} =V _{GS}	T _j =25°C	1.8	2.7	-	V
I _{GSS}	Gate-Source Leakage Current	V _{GS} =20V, V _{DS} =0V	T _j =25°C	-	-	300	nA
R _{DS(on)} (Chip)	Static drain-source	I _D =300A	T _j =25°C	-	7.2	10	mΩ
	On-state resistance	V _{GS} =+15V	T _j =175°C	-	10.3	-	mΩ
V _{DS(on)} (Chip)	Static drain-source	I _D =300A	T _j =25°C	-	2.16	3.0	V
	On-state Voltage	V _{GS} =+15V	T _j =175°C	-	3.09	-	V
C _{iss}	Input Capacitance	V _D =800V, V _{GS} =0V, f =100KHz		-	17.4	-	nF
C _{oss}	Output Capacitance			-	0.53	-	nF
C _{rss}	Reverse transfer Capacitance			-	0.043	-	nF
Q _g	Total gate charge	V _{DD} =800V, I _D =180A, V _{GS} =+15/-5V		-	540	-	nC
t _{d(on)}	Turn-on delay time	V _{DD} =600V I _D =300A V _{GS} =+15/-4V R _{gon} /R _{goff} =5.1/3.3Ω Inductive load switching operation	T _j =25°C	-	41	-	ns
			T _j =150°C	-	39	-	
t _r	Rise time		T _j =25°C	-	23	-	ns
			T _j =150°C	-	18	-	
t _{d(off)}	Turn-off delay time		T _j =25°C	-	109	-	ns
			T _j =150°C	-	117	-	
t _f	Fall time		T _j =25°C	-	13	-	ns
			T _j =150°C	-	37	-	
E _{on}	Turn-on power dissipation		T _j =25°C	-	8.29	-	mJ
			T _j =150°C	-	8.50	-	
E _{off}	Turn-off power dissipation		T _j =25°C	-	3.23	-	mJ
			T _j =150°C	-	3.53	-	
R _{th(j-c)}	FET Thermal Resistance	Junction to Case		-	0.115	-	K/W
R _{th(c-f)}	Contact thermal Resistance	With thermal conductive grease, Note3		-	0.015	-	K/W

Note3: Assumes Thermal Conductivity of grease is 0.9W/m·K and thickness is 50um.

Body Diode Electrical characteristics (T_j=25°C unless otherwise specified, chip)

Symbol	Item	Condition		Value			Unit
				Min.	Typ.	Max	
V _{SD}	Body Diode Forward Voltage	V _{GS} = -5V	T _j = 25°C	-	5.2	-	V
		I _{SD} = 300A	T _j = 175°C	-	4.3	-	
T _{rr}	Reverse recovery time	V _{DD} = 600V	T _j = 25°C	-	24	-	ns
		I _D = 300A	T _j = 150°C	-	47	-	
Q _{rr}	Reverse recovery charge	V _{GS} = +15/-4V	T _j = 25°C	-	1.1	-	μC
		R _{gon} /R _{goff} = 5.1/3.3Ω	T _j = 150°C	-	4.7	-	
E _{rr}	Diode switching power dissipation	Inductive load switching operation	T _j = 25°C	-	0.82	-	mJ
			T _j = 150°C	-	2.03	-	

Test Conditions

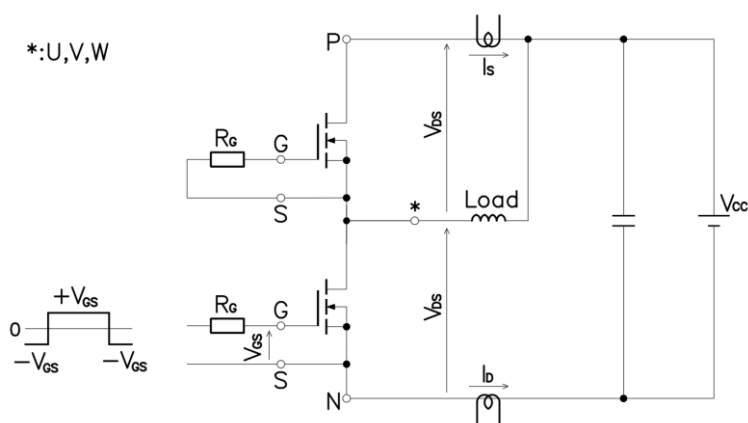


Figure 3. Switching time measure circuit

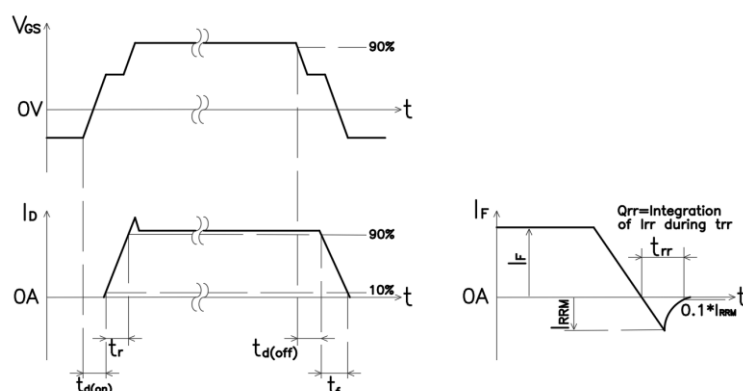


Figure 4. Switching time definition

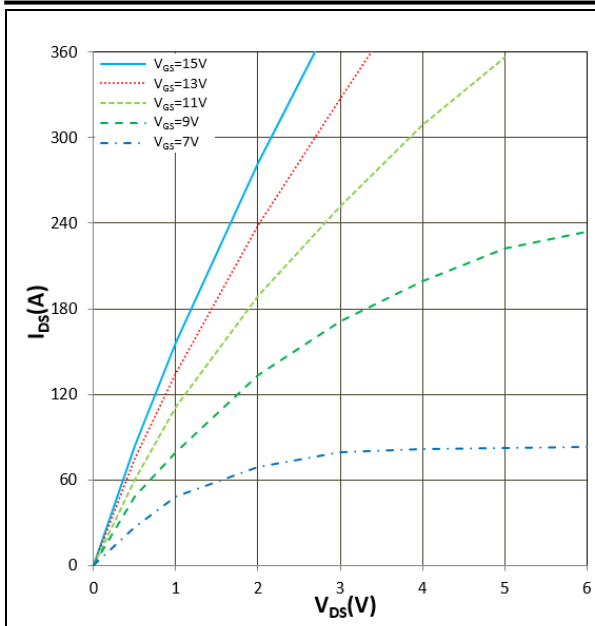


Figure 5. I_{DS} vs V_{DS}
 $T_j = 25^\circ\text{C}$

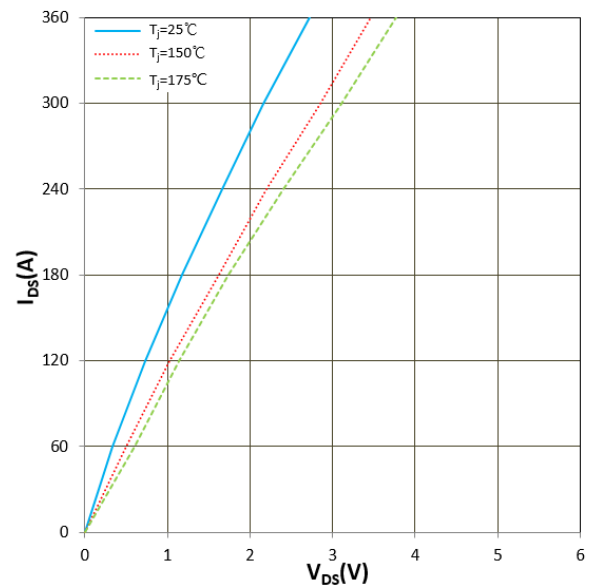


Figure 6. I_{DS} vs V_{DS}
 $V_{GS} = +15\text{V}$

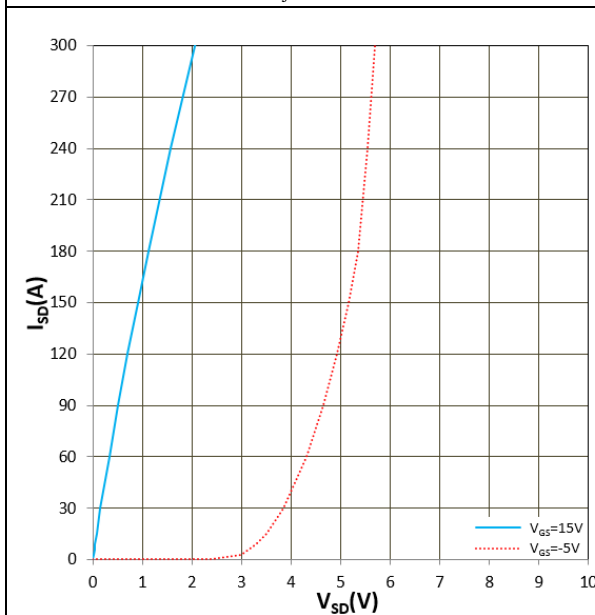


Figure 7. I_{SD} vs V_{SD} (V_F)
 $T_j = 25^\circ\text{C}$

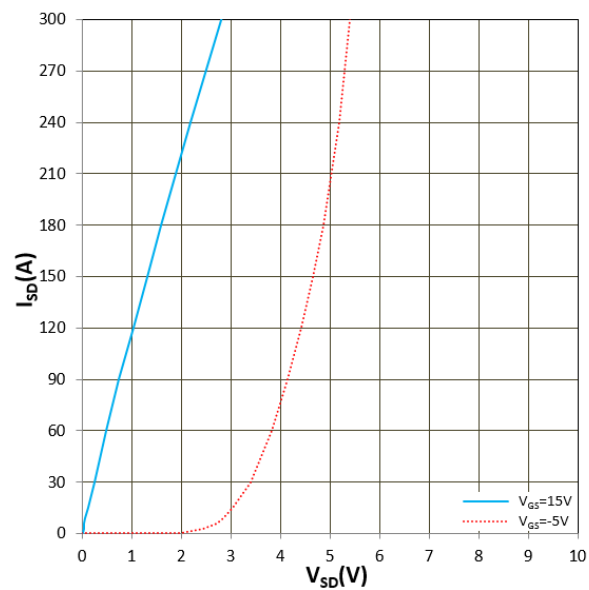


Figure 8. I_{SD} vs V_{SD} (V_F)
 $T_j = 175^\circ\text{C}$

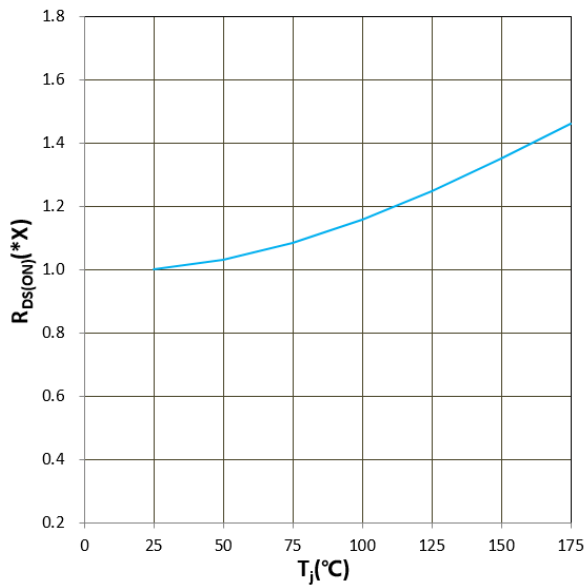


Figure 9. $R_{DS(on)}$ vs T_j
 $V_{GS} = +15\text{V}$, $I_D = 300\text{A}$, $1.0X = 7.2\text{m}\Omega$

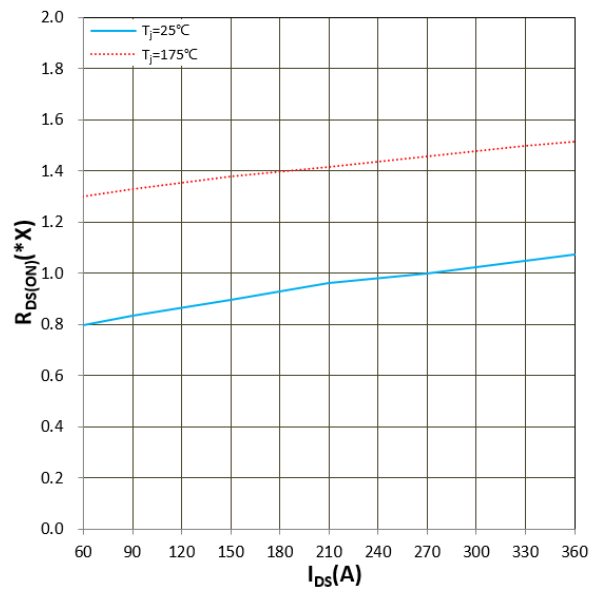


Figure 10. $R_{DS(on)}$ vs I_{DS}
 $V_{GS} = +15\text{V}$, $I_D = 300\text{A}$, $1.0X = 7.2\text{m}\Omega$

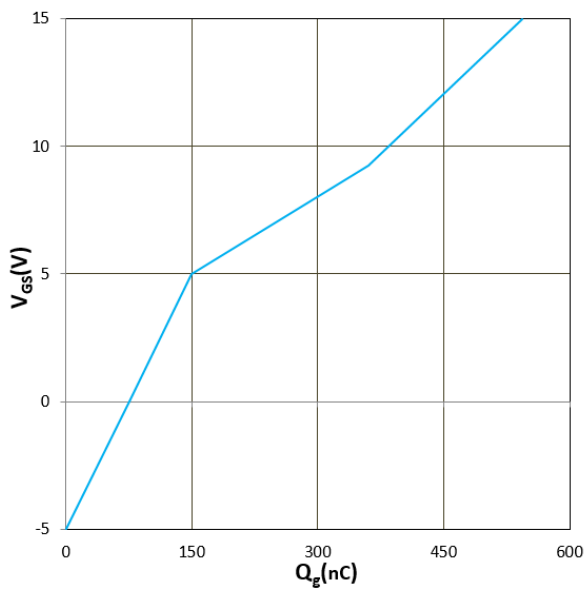


Figure 11. V_{GS} vs Q_g
 $V_{DS} = 800\text{V}$, $I_D = 180\text{A}$, $T_j = 25^{\circ}\text{C}$

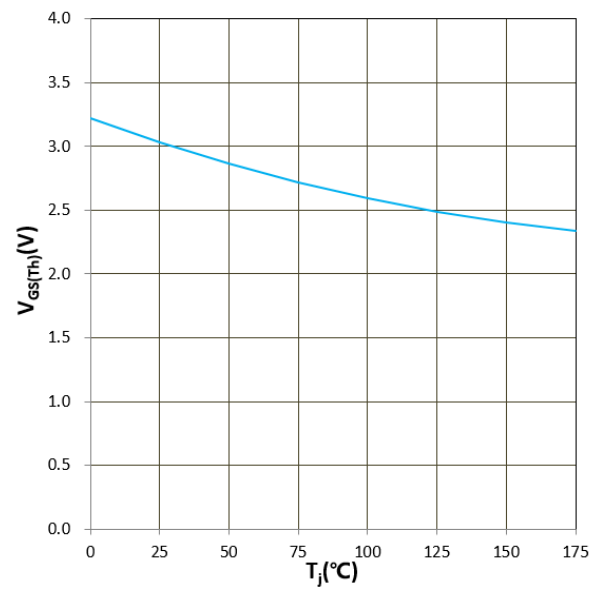


Figure 12. $V_{GS(th)}$ vs T_j
 $V_{GS} = V_{DS}$, $I_D = 105\text{mA}$

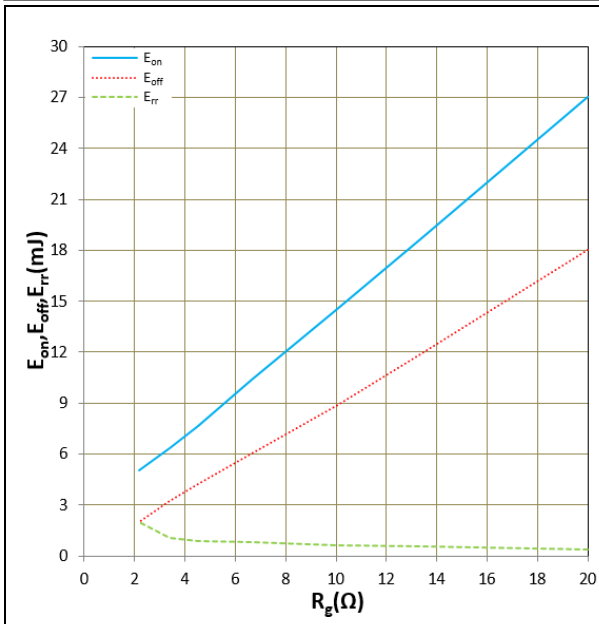


Figure 13. E_{on} , E_{off} , E_{rr} vs R_g
 $T_j = 25^\circ\text{C}$, $V_{CC} = 600\text{V}$, $V_{GS} = +15\text{V}/-4\text{V}$, $I_D = 300\text{A}$
 Inductive Load

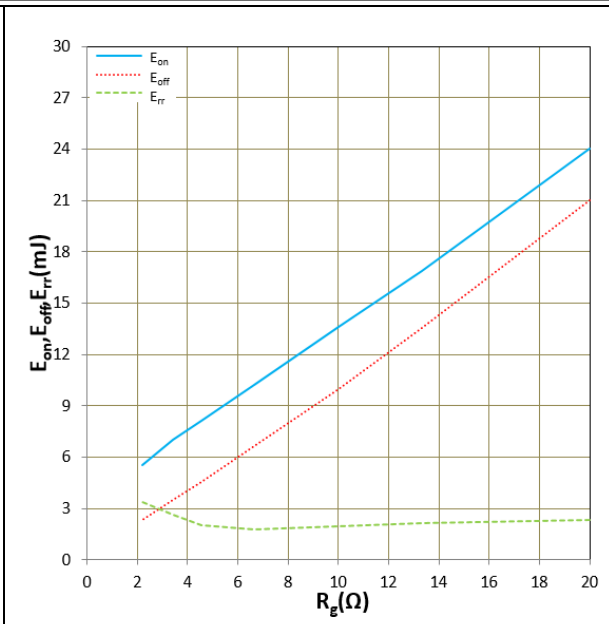


Figure 14. E_{on} , E_{off} , E_{rr} vs R_g
 $T_j = 150^\circ\text{C}$, $V_{CC} = 600\text{V}$, $V_{GS} = +15\text{V}/-4\text{V}$, $I_D = 300\text{A}$
 Inductive Load

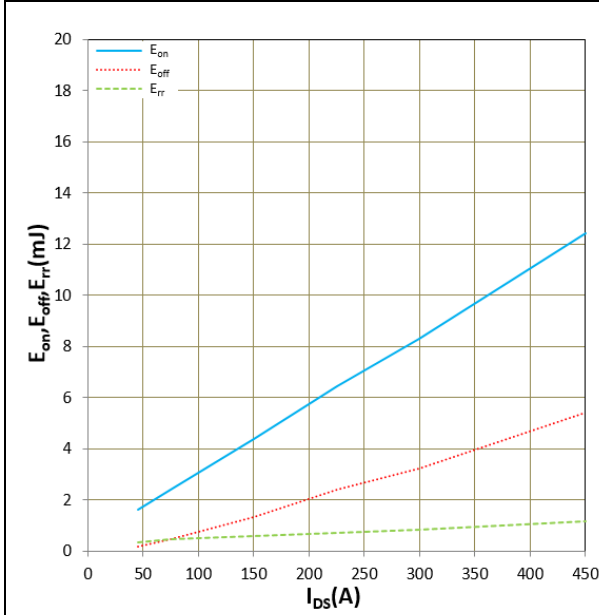


Figure 15. E_{on} , E_{off} , E_{rr} vs I_{DS}
 $T_j = 25^\circ\text{C}$, $V_{CC} = 600\text{V}$, $V_{GS} = +15\text{V}/-4\text{V}$
 $R_{gon}/R_{goff} = 5.1/3.3\Omega$, Inductive Load

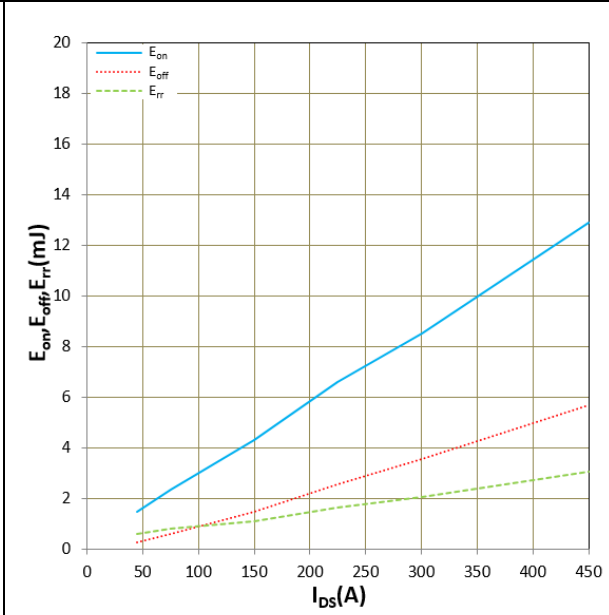


Figure 16. E_{on} , E_{off} , E_{rr} vs I_{DS}
 $T_j = 150^\circ\text{C}$, $V_{CC} = 600\text{V}$, $V_{GS} = +15\text{V}/-4\text{V}$
 $R_{gon}/R_{goff} = 5.1/3.3\Omega$, Inductive Load

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